



DMWSH120H28SM3Q

1200V N-CHANNEL SILICON CARBIDE POWER MOSFET

Product Summary

BV _{DSS} R _{DS(ON) Max}		I _D T _C = +25°C	
1200V	28.5mΩ @V _{GS} = 15V	97.4A	

Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMWSH120H28SM3Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

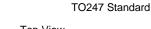
Description and Applications

This SiC MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- EV high-power DC-DC converters
- EV charging systems
- AC-DC traction inverters
- Automotive motor drivers

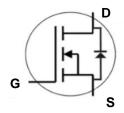
Mechanical Data

- Package: TO247
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Weight: 5.6 grams (Approximate)





Pin Configuration



Internal Schematic

Ordering Information (Note 4)

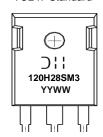
Part Number	Package	Pac	Packing		
Fait Number	Package	Qty.	Carrier		
DMWSH120H28SM3Q	TO247 Standard	30 Pieces	Tube		

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information

TO247 Standard



D: : = Manufacturer's Marking
120H28SM3 = Product Type Marking Code
YYWW or YYWW = Date Code Marking
YY or YY = Last Two Digits of Year (ex: 24 = 2024)
WW or WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		V _{DSS}	1200	V
Gate-Source Voltage (Dynamic)		Vgss	+19/-8	V
Gate-Source Voltage (Static)		Vgss	+15/-4	V
Continuous Drain Current (Notes 5, 6)	$T_C = +25$ °C $T_C = +100$ °C	lo	97.4 68.8	А
Continuous Diode Forward Current (Note 5)	Is	92	Α	
Pulsed Source Current (10µs Pulse, Duty Cycle = 1%) (Note 5)	lsм	410	Α	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) (Note 5)		I _{DM}	410	А

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	Tc = +25°C	Pp	405	W
Total Fower Dissipation (Note 5)	Tc = +100°C	PD	203	
Thermal Resistance, Junction to Ambient (Note 7)		R _{0JA}	29	°C/W
Thermal Resistance, Junction to Case (Note 5)		Rejc	0.37	C/VV
Operating and Storage Temperature Range	TJ, TSTG	-55 to +175	°C	

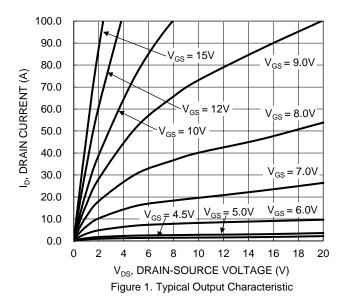
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	1200	_	_	V	$V_{GS} = 0V, I_{D} = 100\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	50	μA	V _{DS} = 1200V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±250	nA	Vgs = +15/-4V, Vps = 0V	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	1.8	2.5	3.6	V	V _{DS} = V _{GS} , I _D = 17.7mA	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	20	28.5	mΩ	$V_{GS} = 15V, I_D = 50A$	
Diode Forward Voltage	VsD	_	3.8	-	V	V _G S = -4V, I _S = 25A	
Transconductance	gfs	_	15	-	S	V _{DS} = 20V, I _D = 50A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	3905	_			
Output Capacitance	Coss	_	184	-	pF	V _G S = 0V, V _D S = 1000V V _A C = 25mV, f = 1MHz	
Reverse Transfer Capacitance	Crss	_	10.2	_			
Coss Stored Energy	Eoss	_	113	_	μJ		
Turn-On Switching Energy (Body Diode Forward)	Eon	_	742	_	μJ		$V_{GS} = -4V/+15V$, $V_{DS} = 800V$
Turn-Off Switching Energy (Body Diode Forward)	Eoff	-	363			$R_g = 5\Omega$, $I_D = 50A$, $L = 157\mu H$	
Gate Resistance	R_g	_	1.3	_	Ω	$V_{AC} = 100 \text{mV}, f = 1 \text{MHz}$	
Total Gate Charge	Qg	_	175	_			
Gate-Source Charge	Qgs	_	48.1	-	n(; l · · · · · · · · · · · · · · · · · ·	$V_{GS} = -4V/+15V$, $V_{DS} = 800V$ $I_{D} = 50A$	
Gate-Drain Charge	Q_{gd}	_	55.3	_		10 - 30A	
Turn-On Delay Time	t _{D(ON)}	_	24.2	_		$V_{GS} = -4V/+15V, V_{DD} = 800V$ $R_g = 5\Omega, L = 157\mu H$	
Turn-On Rise Time	t _R	_	40.6	_			
Turn-Off Delay Time	tD(OFF)	_	44.8	_	ns		
Turn-Off Fall Time	tF	_	12.8	_			
Body Diode Reverse Recovery Time	t _{RR}		22.5	_	ns	N 40 V 2000V	
Body Diode Reverse Recovery Charge	Qrr	_	432	-	$P_{DS} = -4V, V_{DS} = 800V$ $I_{D} = 50A, di/dt = 2600A/\mu s$		
Body Diode Reverse Recovery Current	IRRM	_	30	_	Α	10 - 30Λ, αναι - 2000Λ/μ3	

Notes:

- 5. Device mounted on an infinite heatsink.
- Drain current limited by maximum junction temperature.
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to production testing.





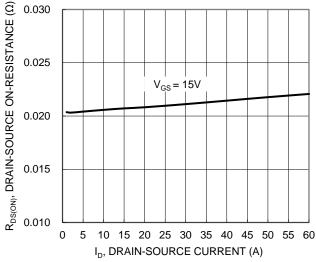


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

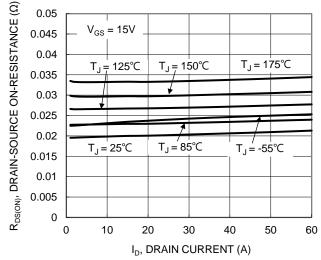


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

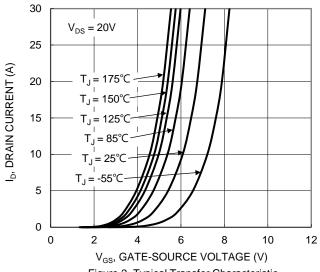


Figure 2. Typical Transfer Characteristic

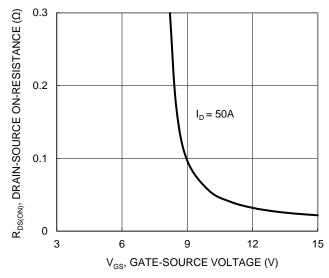


Figure 4. Typical Transfer Characteristic

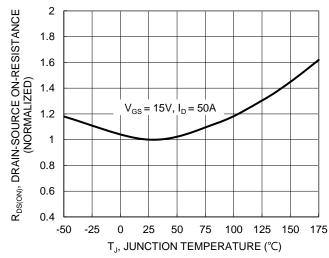


Figure 6. On-Resistance Variation with Junction Temperature





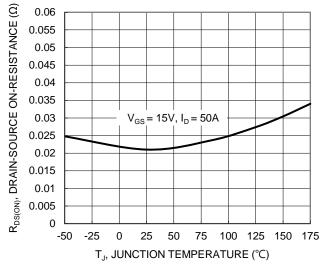


Figure 7. On-Resistance Variation with Junction Temperature

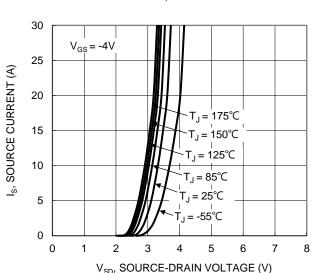


Figure 9. Diode Forward Voltage vs. Current

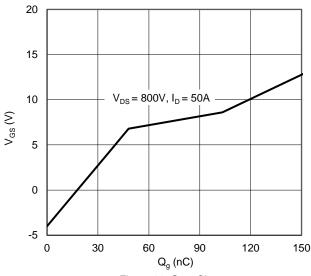


Figure 11. Gate Charge

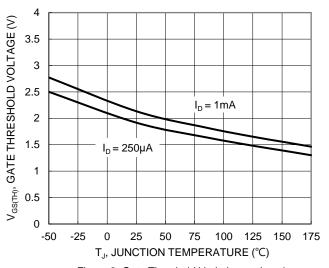


Figure 8. Gate Threshold Variation vs Junction Temperature

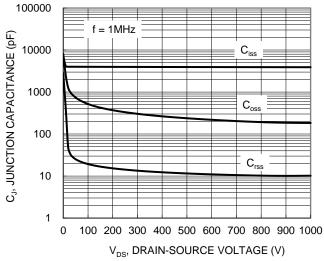


Figure 10. Typical Junction Capacitance

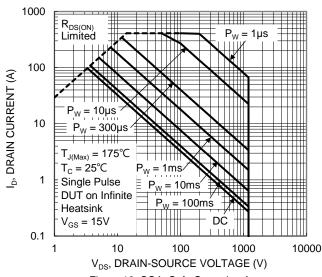


Figure 12. SOA, Safe Operation Area



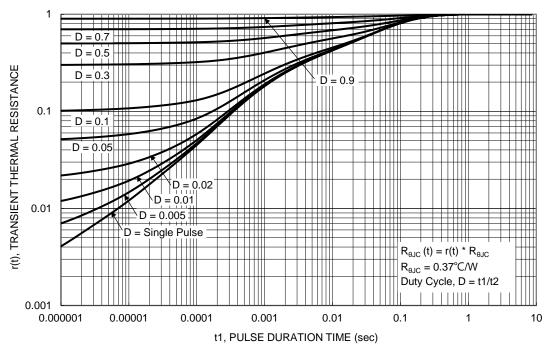


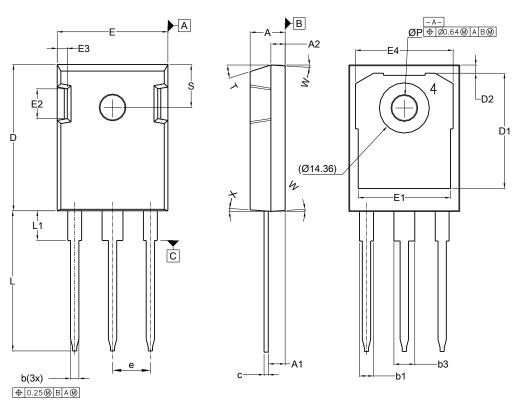
Figure 13. Transient Thermal Resistance



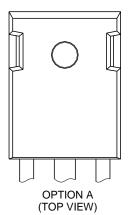
Package Outline Dimensions

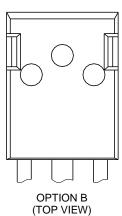
Please see http://www.diodes.com/package-outlines.html for the latest version.

TO247 Standard



TO247 Standard					
Dim	Min	Max	Тур		
Α	4.83	5.21			
A1	2.10	2.54			
A2	1.88	2.16			
b	1.07	1.33			
b1	1.90	2.41			
b3	2.87	3.38			
С	0.51	0.76	0.60		
D	20.80	21.75			
D1	15.88	17.65			
D2	0.95	1.77			
Е	15.75	16.25			
E1	12.38	14.52			
E2	3.68	5.10			
E3	1.00	2.18			
E4	13.10	14.52			
е	5	.44 BSC			
L	19.60	20.32			
L1	3.78	4.40			
PØ	2.90	3.65			
S	6.04	6.80			
Т	17.5-20° REF				
W	3.5-4.5° REF				
Х	4-5° REF				
All Dimensions in mm					







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